## 54F08,74F08

Quad 2-Input AND Gate



Literature Number: SNOS147A

December 1994

54F/74F08

DSXXX

## National Semiconductor

### 54F/74F08 Quad 2-Input AND Gate

### **General Description**

This device contains four independent gates, each of which performs the logic AND function.

### Ordering Code: See Section 0

U					
Commercial	Military	Package	Package Description		
		Number			
74F08PC		N14A	14-Lead (0.300" Wide) Molded Dual-In-Line		
	54F08DM (Note 2)	J14A	14-Lead Ceramic Dual-In-Line		
74F08SC (Note 1)		M14A	14-Lead (0.150" Wide) Molded Small Outline, JEDEC		
74F08SJ (Note 1)		M14D	14-Lead (0.300" Wide) Molded Small Outline, EIAJ		
	54F08FM (Note 2)	W14B	14-Lead Cerpack		
	54F08LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C		

**Features** 

Guaranteed 4000V minimum ESD protection

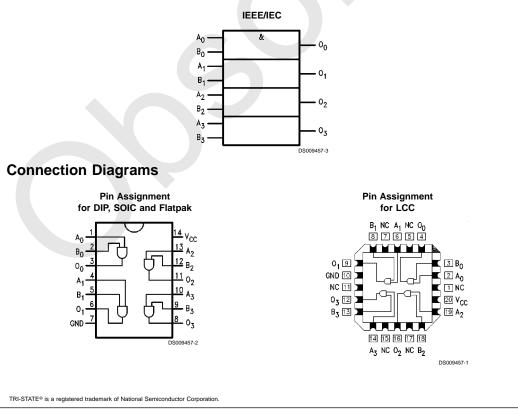
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Note 1: Devices also available in 13" reel. Use suffix = SCX and SJX.

Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

### Logic Symbol

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# Unit Loading/Fan Out See Section 0 for U.L. definitions

		54F/74F			
Pin Names	Description	U.L.	Input I <sub>IH</sub> /I <sub>IL</sub> Output I <sub>OH</sub> /I <sub>OL</sub>		
		HIGH/LOW			
A <sub>n</sub> , B <sub>n</sub>	Inputs	1.0/1.0	20 µA/–0.6 mA		
O <sub>n</sub>	Outputs	50/33.3	–1 mA/20 mA		

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### Absolute Maximum Ratings (Note 3)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Storage Temperature Ambient Temperature under Bias	-65°C to +150°C -55°C to +125°C -55°C to +175°C			
Junction Temperature under Bias Plastic	-55°C to +150°C			
V <sub>CC</sub> Pin Potential to				
Ground Pin	-0.5V to +7.0V			
Input Voltage (Note 4)	-0.5V to +7.0V			
Input Current (Note 4)	-30 mA to +5.0 mA			
Voltage Applied to Output				
in HIGH State (with V <sub>CC</sub> = 0V)				
Standard Output TRI-STATE <sup>®</sup> Output	–0.5V to V $_{\rm CC}$ –0.5V to +5.5V			

Current Applied to Output

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in LOW State (Max) ESD Last Passing Voltage (Min) twice the rated  $I_{OL}$  (mA) 4000 V

## Recommended Operating Conditions

Free Air Ambient Temperature					
Military	-55°C to +125°C				
Commercial	0°C to +70°C				
Supply Voltage					
Military	+4.5V to +5.5V				
Commercial	+4.5V to +5.5V				
<b>Note 3:</b> Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.					
Note 4: Either voltage limit or current limit is sufficient to protect inputs.					

### **DC Electrical Characteristics**

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ol Parameter		54F/74F			Units	V <sub>cc</sub>	Conditions
		Min	Тур	Max			
Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
Input LOW Voltage				0.8	V		Recognized as a LOW Signal
Input Clamp Diode Vol	tage			-1.2	V	Min	$I_{IN} = -18 \text{ mA}$
Output HIGH	54F 10% V <sub>CC</sub>	2.5					$I_{OH} = -1 \text{ mA}$
Voltage	74F 10% V <sub>CC</sub>	2.5			V	Min	I <sub>OH</sub> = -1 mA
	74F 5% V <sub>CC</sub>	2.7					I <sub>OH</sub> = -1 mA
Output LOW	54F 10% V <sub>CC</sub>			0.5	V	Min	I <sub>OL</sub> = 20 mA
Voltage	74F 10% V <sub>CC</sub>			0.5			I <sub>OL</sub> = 20 mA
Input HIGH	54F			20.0	μA	Max	V <sub>IN</sub> = 2.7V
Current	74F			5.0			
Input HIGH Current	54F			100	μA	Max	V <sub>IN</sub> = 7.0V
Breakdown Test	74F			7.0			
Output HIGH	54F			250	μA	Max	$V_{OUT} = V_{CC}$
Leakage Current	74F			50			
Input Leakage	74F	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA
Test							All Other Pins Grounded
Output Leakage	74F			3.75	μA	0.0	V <sub>IOD</sub> = 150 mV
Circuit Current							All Other Pins Grounded
Input LOW Current				-0.6	mA	Max	V <sub>IN</sub> = 0.5V
Output Short-Circuit Current		-60		-150	mA	Max	V <sub>OUT</sub> = 0V
Power Supply Current			5.5	8.3	mA	Max	V <sub>O</sub> = HIGH
Power Supply Current			8.6	12.9	mA	Max	V <sub>O</sub> = LOW
	Input HIGH Voltage Input LOW Voltage Input Clamp Diode Vol Output HIGH Voltage Output LOW Voltage Input HIGH Current Input HIGH Current Breakdown Test Output HIGH Leakage Current Input Leakage Test Output Leakage Circuit Current Input LoW Current Output Short-Circuit Cu Power Supply Current	Input HIGH Voltage Input LOW Voltage Input Clamp Diode Voltage Output HIGH 54F 10% V <sub>CC</sub> Voltage 74F 10% V <sub>CC</sub> 74F 5% V <sub>CC</sub> Output LOW 54F 10% V <sub>CC</sub> Output LOW 54F 10% V <sub>CC</sub> Input HIGH 54F Current 74F Input HIGH Current 54F Breakdown Test 74F Output HIGH 54F Leakage Current 74F Input Leakage 74F Test Output Leakage 74F Circuit Current Input Low Current Input LOW Current Output Short-Circuit Current Power Supply Current	Min   Input HIGH Voltage 2.0   Input LOW Voltage 2.0   Input Clamp Diode Voltage 2.0   Output HIGH 54F 10% V <sub>CC</sub> 2.5   Voltage 74F 10% V <sub>CC</sub> 2.5   74F 5% V <sub>CC</sub> 2.7   Output LOW 54F 10% V <sub>CC</sub> 2.7   Input HIGH 54F 2.7   Input HIGH 54F 4.75   Input HIGH Current 54F 4.75   Breakdown Test 74F 4.75   Input Leakage 74F 4.75   Test V 74F 4.75   Output Leakage 74F 4.75   Test V 4.75   Output Low Current -60   Power Supply Current -60	MinTypInput HIGH Voltage2.0Input LOW Voltage2.0Input Clamp Diode Voltage2.5Output HIGH54F 10% V <sub>CC</sub> 2.574F 5% V <sub>CC</sub> 2.7Output LOW54F 10% V <sub>CC</sub> 2.7Output LOW54F 10% V <sub>CC</sub> 1Voltage74F 10% V <sub>CC</sub> 1Input HIGH54F1Current74F1Input HIGH Current54F1Breakdown Test74F1Output HIGH54F1Leakage Current74F1Input Leakage74F4.75Test01Output LoW Current-60Power Supply Current5.5	Min     Typ     Max       Input HIGH Voltage     2.0     0.8       Input Clamp Diode Voltage     2.5     -1.2       Output HIGH     54F 10% V <sub>CC</sub> 2.5     -1.2       Output HIGH     54F 10% V <sub>CC</sub> 2.5     -1.2       Output HIGH     54F 10% V <sub>CC</sub> 2.5     -1.2       Output LOW     54F 10% V <sub>CC</sub> 2.7     -0.5       Input HIGH     54F     0.5     0.5       Input HIGH     54F     20.0     -0.5       Current     74F     5.0     100       Breakdown Test     74F     7.0     250       Leakage Current     74F     50     50       Input Leakage     74F     4.75     50       Test     -0.6     -0.6     -0.6       Output Leakage     74F     -0.6     -150          <	Min     Typ     Max       Input HIGH Voltage     2.0     V       Input LOW Voltage     2.0     0.8     V       Input Clamp Diode Voltage     -1.2     V       Output HIGH     54F 10% V <sub>CC</sub> 2.5     -1.2     V       Output HIGH     54F 10% V <sub>CC</sub> 2.5     -1.2     V       Output LOW     54F 10% V <sub>CC</sub> 2.5     -     V       Output LOW     54F 10% V <sub>CC</sub> 2.7     -     V       Output LOW     54F 10% V <sub>CC</sub> 2.7     -     V       Output LOW     54F 10% V <sub>CC</sub> 2.7     -     -       Output LOW     54F 10% V <sub>CC</sub> 0.5     V     -       Output HIGH     54F     0.5     0.5     V       Input HIGH Current     54F     100     μA       Breakdown Test     74F     7.0     -       Output HIGH     54F     250     μA       Leakage Current     74F     4.75     V       Test     -0.6     mA     -0.6	Min     Typ     Max     V       Input HIGH Voltage     2.0     V     V       Input LOW Voltage     0.8     V     V       Input Clamp Diode Voltage     -1.2     V     Min       Output HIGH     54F 10% V <sub>CC</sub> 2.5     V     Min       Output HIGH     54F 10% V <sub>CC</sub> 2.5     V     Min       Output LOW     54F 10% V <sub>CC</sub> 2.7     V     Min       Output LOW     54F 10% V <sub>CC</sub> 2.7     V     Min       Output LOW     54F 10% V <sub>CC</sub> 0.5     V     Min       Voltage     74F 10% V <sub>CC</sub> 0.5     V     Min       Voltage     74F 10% V <sub>CC</sub> 0.5     V     Min       Input HIGH     54F     20.0     μA     Max       Current     74F     5.0      Max       Input HIGH Current     54F     100     μA     Max       Leakage Current     74F     50     V     0.0       Test     74F     4.75     V

### **AC Electrical Characteristics**

See Section 0 for Waveforms and Load Configurations

	Parameter	74F		54F T <sub>A</sub> , V <sub>CC</sub> = Mil C <sub>L</sub> = 50 pF		74F T <sub>A</sub> , V <sub>CC</sub> = Com C <sub>L</sub> = 50 pF		Units	Fig. No.	
Symbol		$T_A = +25$ °C $V_{CC} = +5.0V$								
		C <sub>L</sub> = 50 pF								
		Min	Тур	Max	Min	Max	Min	Max		
t <sub>PLH</sub>	Propagation Delay	3.0	4.2	5.6	2.5	7.5	3.0	6.6	ns	<b>**-**</b>
t <sub>PHL</sub>	A <sub>n</sub> , B <sub>n</sub> to O <sub>n</sub>	2.5	4.0	5.3	2.0	7.5	2.5	6.3		

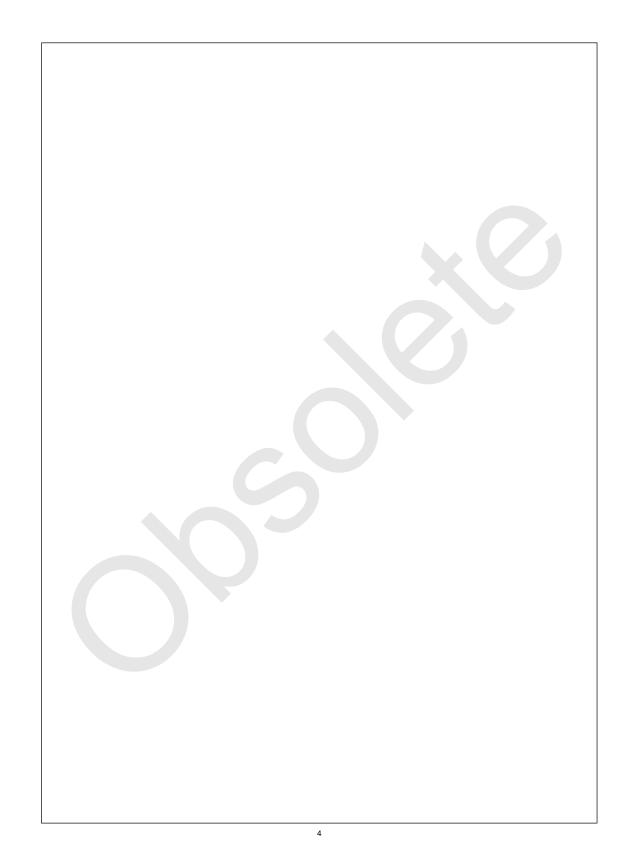
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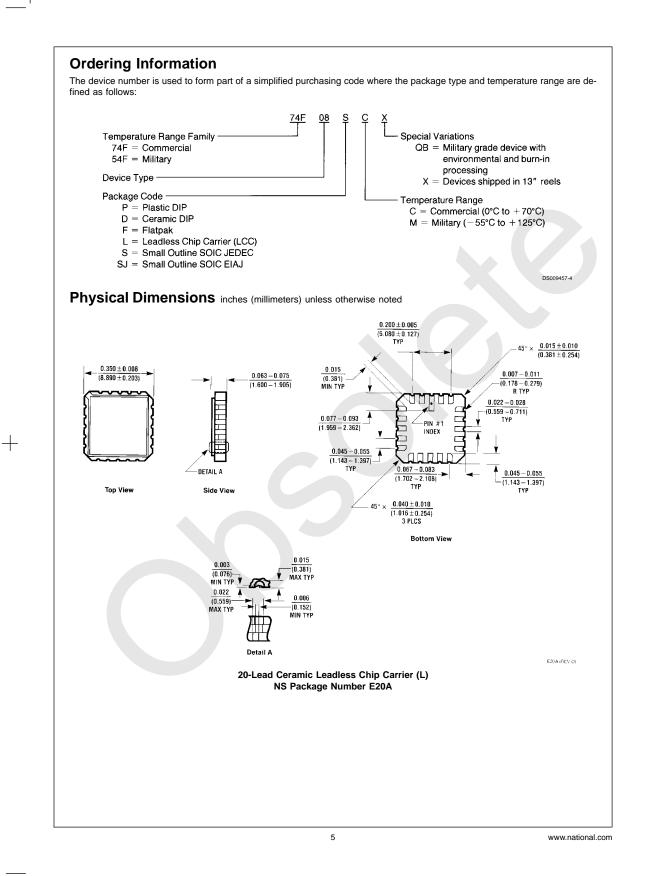
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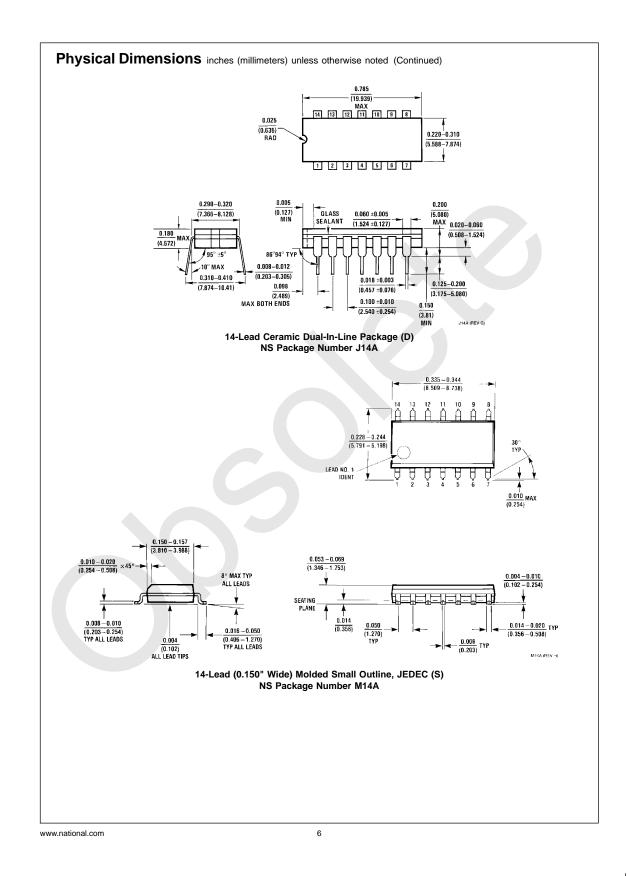
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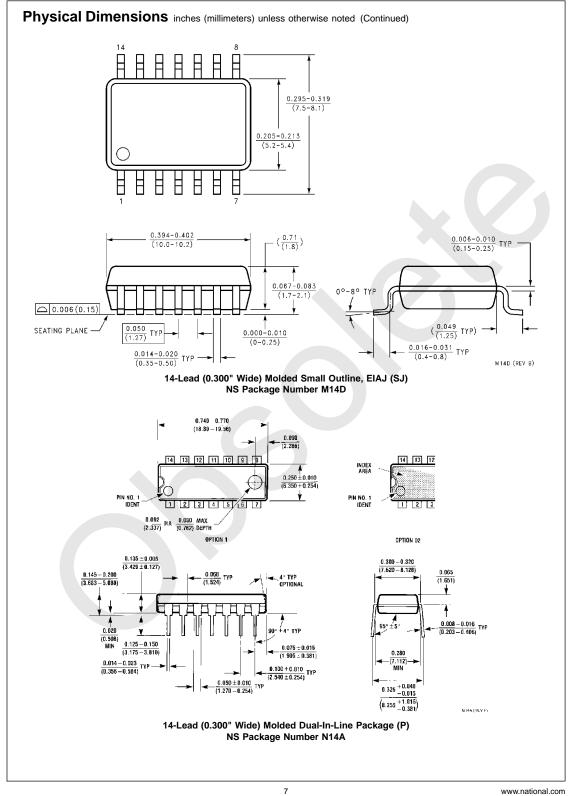
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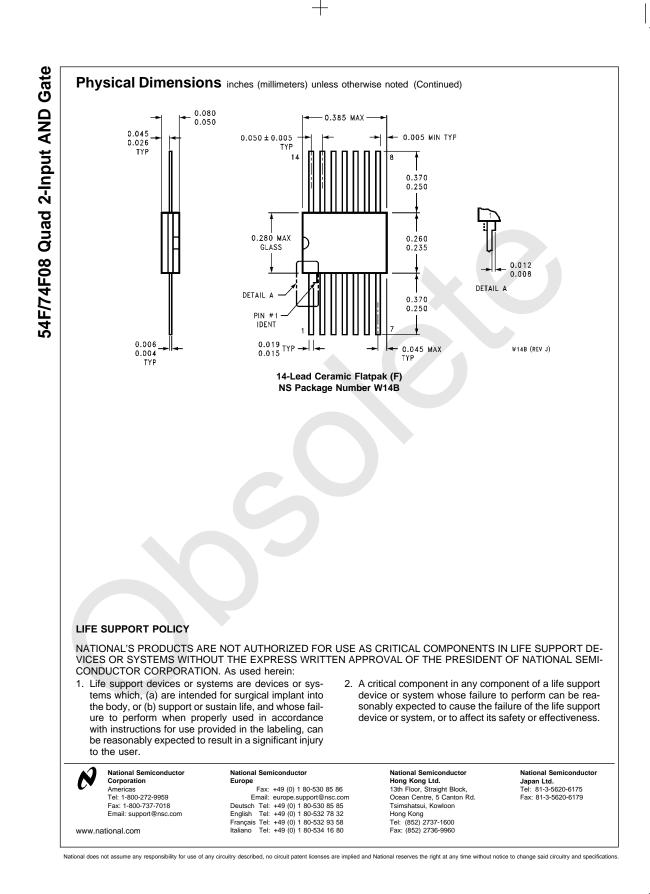


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